

PATENT  
3313-1099P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant:      CHANG, Shu-Ming et al      Conf.:  
Appl. No.:      NEW      Group:  
Filed:      January 29, 2004      Examiner:  
For:      WAFER    LEVEL    CHIP    SCALE    PACKAGING  
             STRUCTURE AND METHOD OF FABRICATING THE  
             SAME

PRELIMINARY AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

January 29, 2004

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

This amendment includes Amendments to the Specification and Remarks.